



Material Content Data Sheet



Sales Product Name		SPB17N80C3		Issued		19. July 2018		
MA#		MA001590172						
Package		PG-TO263-3-2		Weight*		1566.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.969	0.83	0.83	8277	8277
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		194	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	copper	7440-50-8	304.026	19.40	19.43	194024	194276
wire	non noble metal	aluminium	7429-90-5	28.283	1.80	1.80	18050	18050
encapsulation	organic material	carbon black	1333-86-4	9.827	0.63		6271	
	plastics	epoxy resin	-	108.092	6.90		68982	
	inorganic material	silicondioxide	60676-86-0	537.184	34.28	41.81	342822	418075
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6163	6163
plating	non noble metal	nickel	7440-02-0	0.228	0.01		146	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	146
solder	noble metal	silver	7440-22-4	0.198	0.01		126	
	non noble metal	tin	7440-31-5	0.158	0.01		101	
	non noble metal	lead	7439-92-1	7.553	0.48	0.50	4821	5048
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		350	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	copper	7440-50-8	547.666	34.95	35.00	349509	349965
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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